Ultra-Low On-Resistance, 4-A Integrated Load Switch with Controlled Turn-on

Check for Samples: TPS22920

FEATURES

- **Integrated Load Switch**
- **Input Voltage Range: 0.75-V to 3.6-V**
- **Integrated Pass-FET r_{DSON} = 2mΩ (typ) at 3.6-V**
- **Ultra-Low ON-Resistance**
  - **r_{ON} = 5.3-mΩ at 3.6-V**
  - **r_{ON} = 5.4-mΩ at 2.5-V**
  - **r_{ON} = 5.5-mΩ at 1.8-V**
  - **r_{ON} = 5.8-mΩ at 1.2-V**
  - **r_{ON} = 6.1-mΩ at 1.05-V**
  - **r_{ON} = 7.3-mΩ at 0.75-V**
- **Ultra Small CSP-8 package 0.9mm×1.9mm, 0.5mm pitch**
- **4-A Maximum Continuous Switch Current**
- **Shutdown Current 5.5-µA max**
- **Low Threshold Control Input**
- **Controlled slew- rate to avoid inrush current**
- **Quick Output Discharge Transistor**
- **ESD Performance Tested Per JESD 22**
  - **4000-V Human-Body Model (A114-B, Class II)**
  - **1000-V Charged-Device Model (C101)**

APPLICATIONS

- **Notebook / Netbook Computer**
- **Tablet PC**
- **PDAs / Smartphones**
- **GPS Navigation Devices**
- **MP3 Players**

DESCRIPTION

The TPS22920 is a small, ultra-low r_{ON} load switch with controlled turn on. The device contains a N-channel MOSFET that can operate over an input voltage range of 0.75 V to 3.6 V and switch currents up to 4-A. An integrated charge pump biases the NMOS switch in order to achieve a minimum switch ON resistance (r_{ON}). The switch is controlled by an on/off input (ON), which is capable of interfacing directly with low-voltage control signals.

The TPS22920 has a 1250-Ω on-chip load resistor for quick output discharge when the switch is turned off.

The TPS22920 has an internally controlled rise time in order to reduce inrush current. The TPS22920 features a rise time of 880µS at 3.6-V.

The TPS22920 is available in an ultra-small, space-saving 8-pin CSP package and is characterized for operation over the free-air temperature range of –40°C to 85°C.

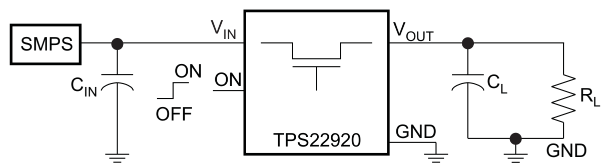


Figure 1. Typical Application

FEATURE LIST

	r_{ON} (typ) at 3.6 V	RISE TIME (typ) at 3.6V	QUICK OUTPUT DISCHARGE(1)	MAXIMUM OUTPUT CURRENT	ENABLE
TPS22920	5.3- mΩ	880 µS	Yes	4-A	Active High

(1) This feature discharges the output of the switch to ground through a 1250-Ω resistor, preventing the output from floating. See Application section 'Output Pull-Down'

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

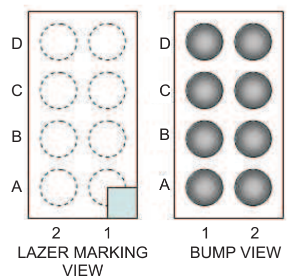


Figure 2. Bump Assignments

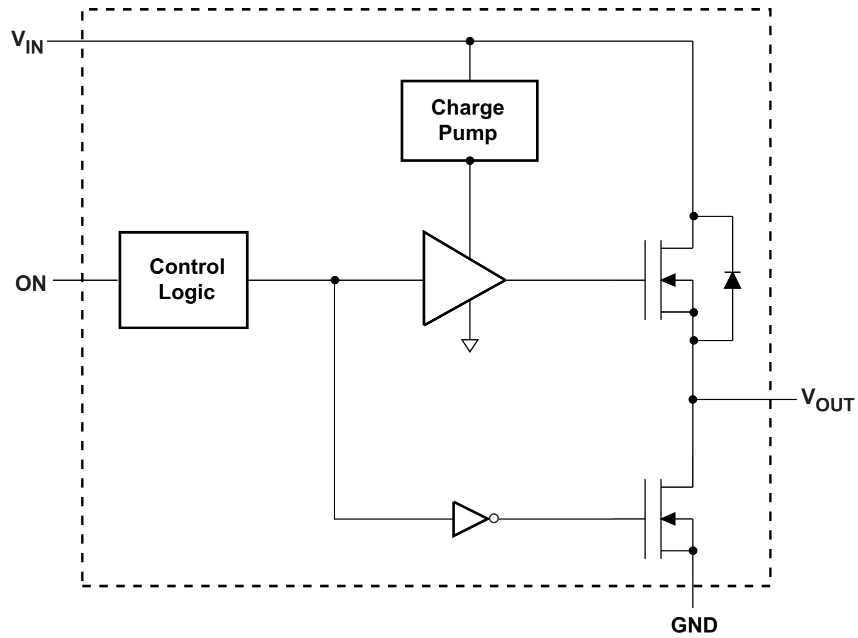
Bump Assignments (YZP Package)

D	GND	ON
C	V_{OUT}	V_{IN}
B	V_{OUT}	V_{IN}
A	V_{OUT}	V_{IN}
	1	**2**

Pin Description

TPS22920	PIN NAME	DESCRIPTION
YZP		
D1	GND	Ground
D2	ON	Switch control input, active high. Do not leave floating
A1, B1, C1	VOUT	Switch output
A2, B2, C2	VIN	Switch input, bypass this input with a ceramic capacitor to ground

FUNCTIONAL BLOCK DIAGRAM



FUNCTION TABLE

ON	VIN to VOUT	VOUT to GND[(1)]
L	OFF	ON
H	ON	OFF

(1) See Application section 'Output Pull-Down'

ABSOLUTE MAXIMUM RATINGS[(1)]

			VALUE	UNIT
V_{IN}	Input voltage range		–0.3 to 4	V
V_{OUT}	Output voltage range		VIN + 0.3	V
V_{ON}	Input voltage range		–0.3 to 4	V
I_{MAX}	Maximum Continuous Switch Current		4	A
I_{PLS}	Maximum Pulsed Switch Current, pulse <300µS, 2% duty cycle		6	A
T_A	Operating free-air temperature range		–40 to 85	°C
T_J	Maximum junction temperature		125	°C
T_{STG}	Storage temperature range		–65 to 150	°C
T_{LEAD}	Maximum lead temperature (10-s soldering time)		300	°C
ESD	Electrostatic discharge protection	Human-Body Model (HBM)	4000	V
		Charged Device Model (CDM)	1000	

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

THERMAL INFORMATION

THERMAL METRIC[1]		TPS22920 CS130P (8 PINS)	UNITS
θ_{JA}	Junction-to-ambient thermal resistance	130	°C/W
θ_{JCtop}	Junction-to-case (top) thermal resistance	54	
θ_{JB}	Junction-to-board thermal resistance	51	
ψ_{JT}	Junction-to-top characterization parameter	1	
ψ_{JB}	Junction-to-board characterization parameter	50	
θ_{JCbot}	Junction-to-case (bottom) thermal resistance	n/a	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

RECOMMENDED OPERATING CONDITIONS

			MIN	MAX	UNIT
V_{IN}	Input voltage range		0.75	3.6	V
V_{OUT}	Output voltage range			V_{IN}	V
V_{IH}	High-level input voltage, ON	V_{IN} = 2.5-V to 3.6 V	1.2	3.6	V
		V_{IN} = 0.75-V to 2.49 V	0.9	3.6	V
V_{IL}	Low-level input voltage, ON	V_{IN} = 2.5-V to 3.6 V		0.6	V
		V_{IN} = 0.75-V to 2.49 V		0.4	V
C_{IN}	Input Capacitor		1[1]		µF

(1) See *Input Capacitor* section in Application Information.

ELECTRICAL CHARACTERISTICS

V_{IN} = 0.75 V to 3.6 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A	MIN	TYP[1]	MAX	UNIT
I_{IN}	Quiescent Current	I_{OUT} = 0, V_{IN} = V_{ON}	V_{IN} = 3.6 V	Full		68	160	µA
			V_{IN} = 2.5 V			40	70	
			V_{IN} = 1.8 V			25	350	µA
			V_{IN} = 1.2 V			103	200	
			V_{IN} = 1.05 V			78	110	µA
			V_{IN} = 0.75 V			37	70	
$I_{IN(leak)}$	Off Supply Current (After Pull Down)	V_{ON} = GND, V_{OUT} = 0		Full			5.5	µA
r_{ON}	On-Resistance	V_{IN} = 3.6 V, I_{OUT} = –200 mA		25°C		5.3	8.8	mΩ
				Full			9.8	
		V_{IN} = 2.5 V, I_{OUT} = –200 mA		25°C		5.4	8.9	mΩ
				Full			9.9	
		V_{IN} = 1.8 V, I_{OUT} = –200 mA		25°C		5.5	9.1	mΩ
				Full			10.1	
		V_{IN} = 1.2 V, I_{OUT} = –200 mA		25°C		5.8	9.4	mΩ
				Full			10.4	
		V_{IN} = 1.05 V, I_{OUT} = –200 mA		25°C		6.1	9.7	mΩ
				Full			10.8	
		V_{IN} = 0.75 V, I_{OUT} = –200 mA		25°C		7.3	11.0	mΩ
				Full			12.4	
RPD	Output pull down resistance[2]	V_{IN} = 3.3 V, V_{ON} = 0, I_{OUT} = 3 mA		Full		1250	1500	Ω
I_{ON}	ON input leakage current	V_{ON} = 0.9 V to 3.6 V or GND		Full			0.1	µA

(1) Typical values are at V_{IN} = 3.3 V and T_A = 25°C.
(2) See Output Pulldown in *Application Information*.

SWITCHING CHARACTERISTICS

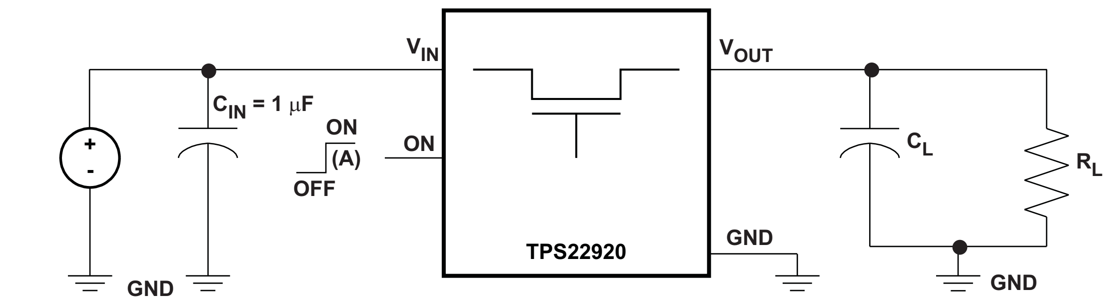
V_{IN} = 3.6 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
t_{ON}	Turn-ON time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 3.6 V		970		µs
t_{OFF}	Turn-OFF time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 3.6 V		3		
t_r	VOUT Rise time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 3.6 V		880		
t_f	VOUT Fall time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 3.6 V		2		

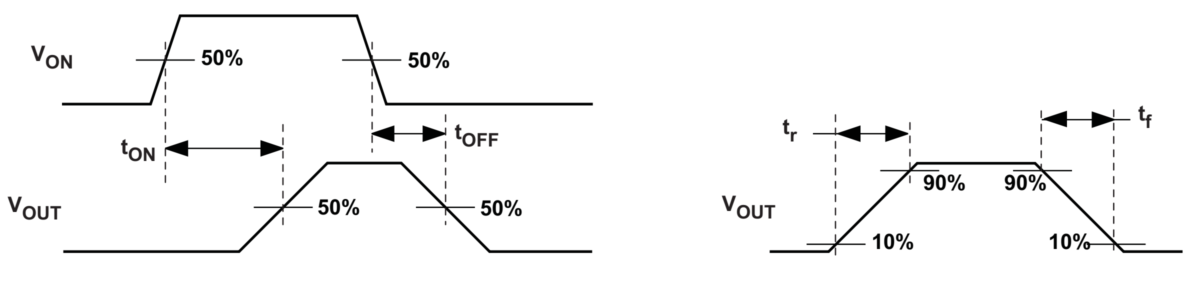
V_{IN} = 0.9 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
t_{ON}	Turn-ON time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 0.9 V		840		µs
t_{OFF}	Turn-OFF time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 0.9 V		16		
t_r	VOUT Rise time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 0.9 V		470		
t_f	VOUT Fall time	R_L = 10 Ω, C_L = 0.1 µF, V_{IN} = 0.9 V		5		

PARAMETRIC MEASUREMENT INFORMATION



TEST CIRCUIT



t_{ON}/t_{OFF} WAVEFORMS

(A) Rise and fall times of the control signal is 100 ns.

Figure 3. Test Circuit and t_{ON}/t_{OFF} Waveforms

TYPICAL CHARACTERISTICS

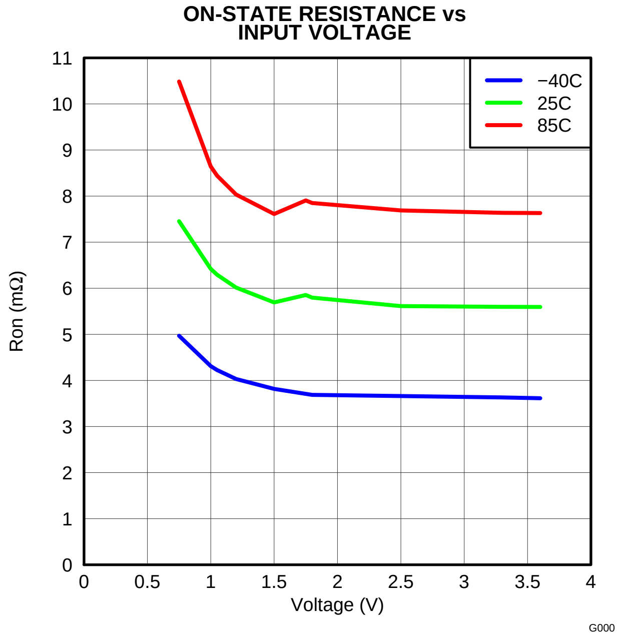


Figure 4.

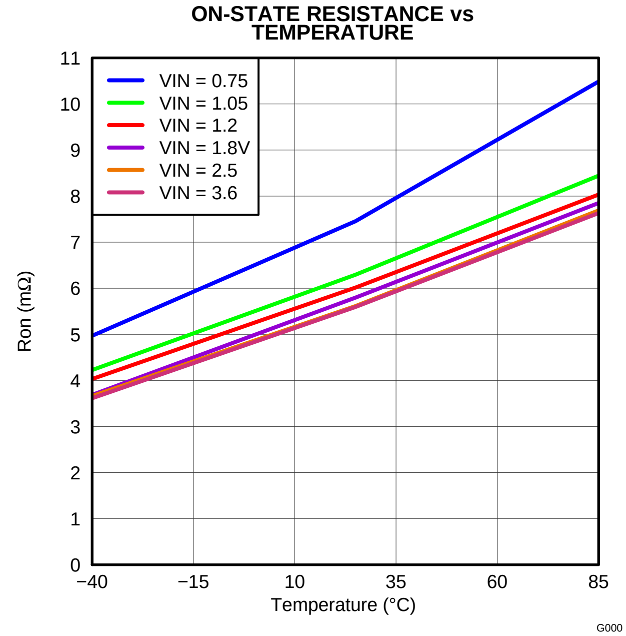


Figure 5.

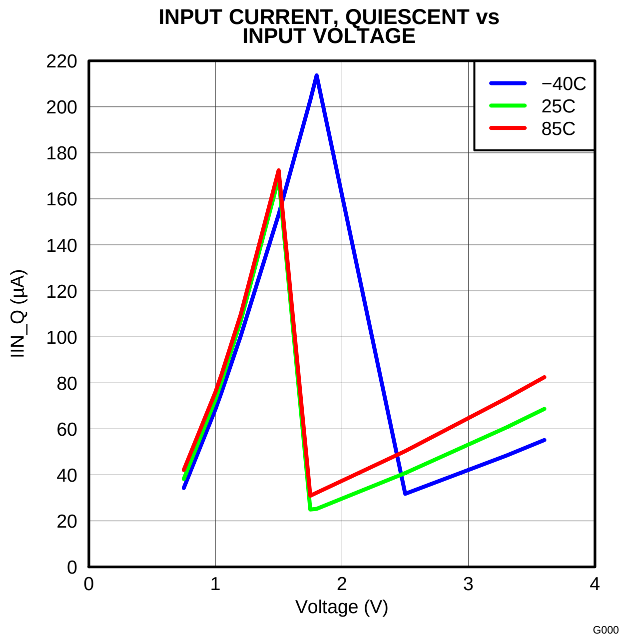


Figure 6.

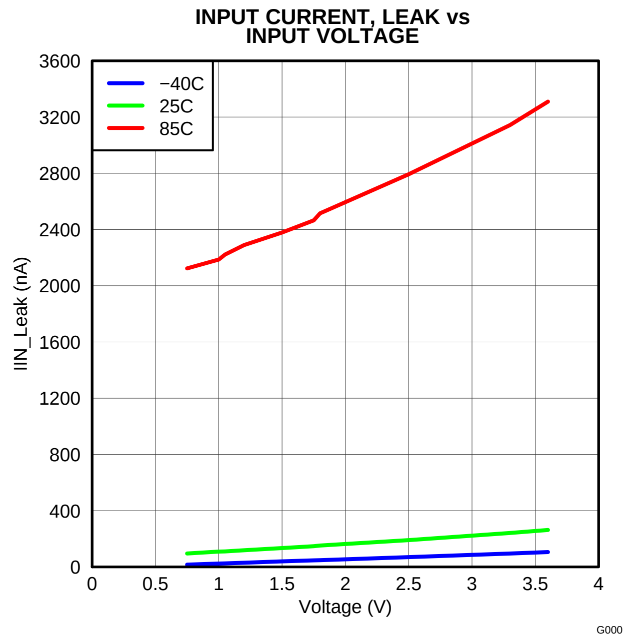


Figure 7.

TYPICAL CHARACTERISTICS (continued)

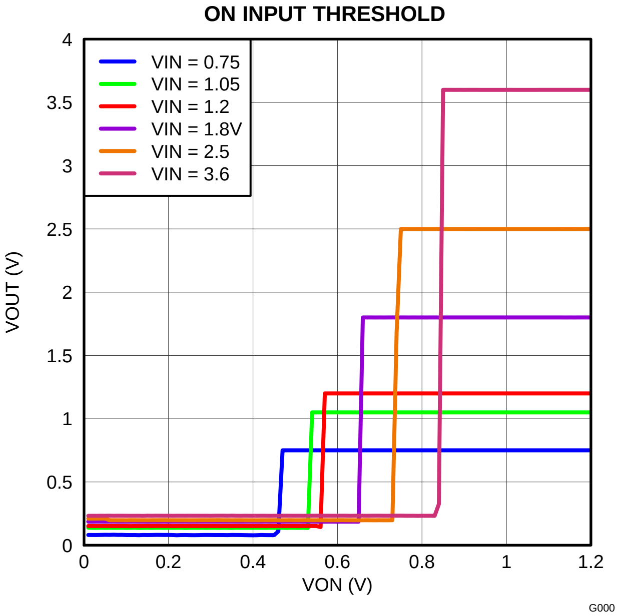


Figure 8.

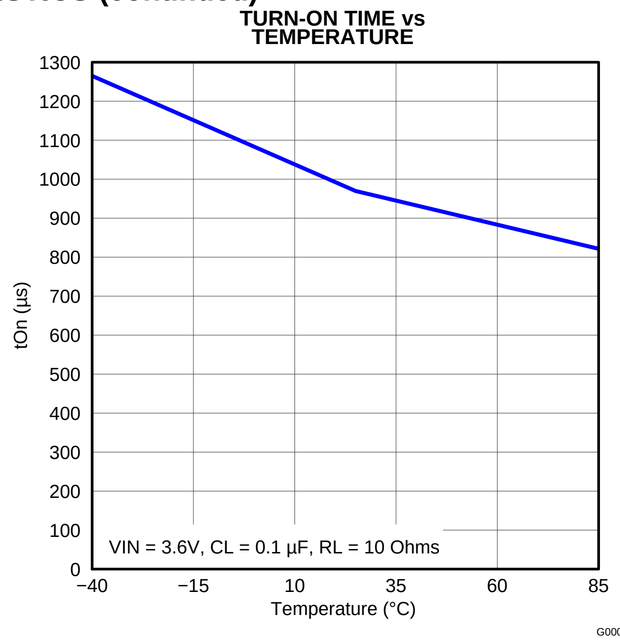


Figure 9.

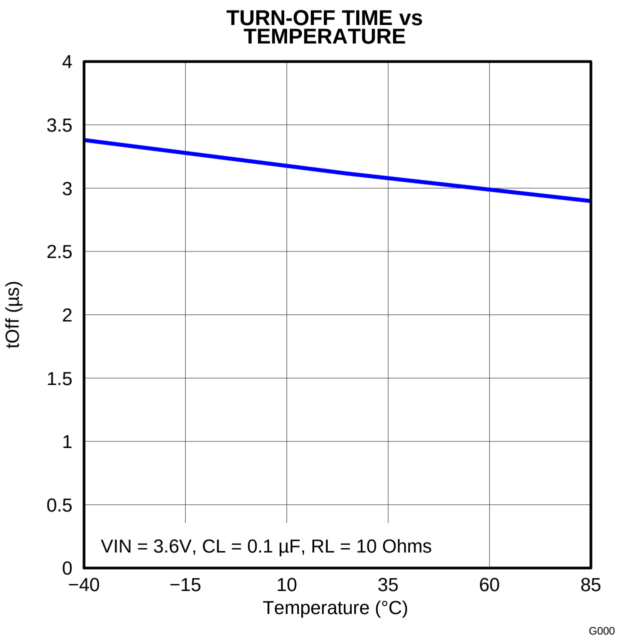


Figure 10.

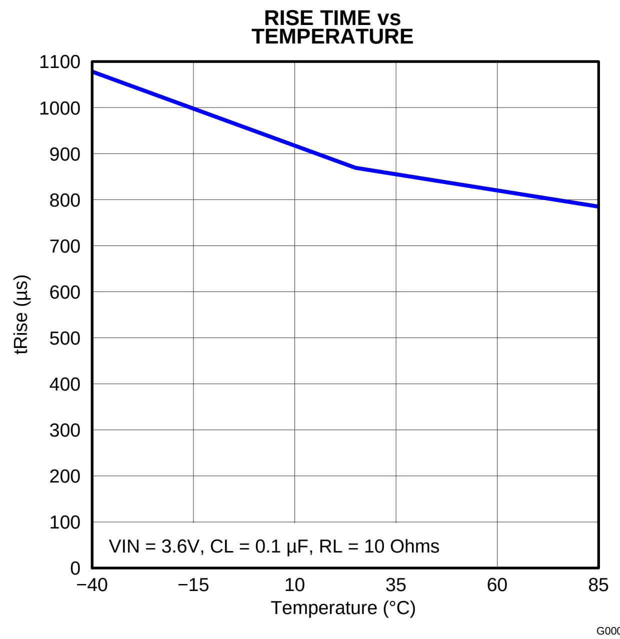


Figure 11.

TYPICAL CHARACTERISTICS (continued)

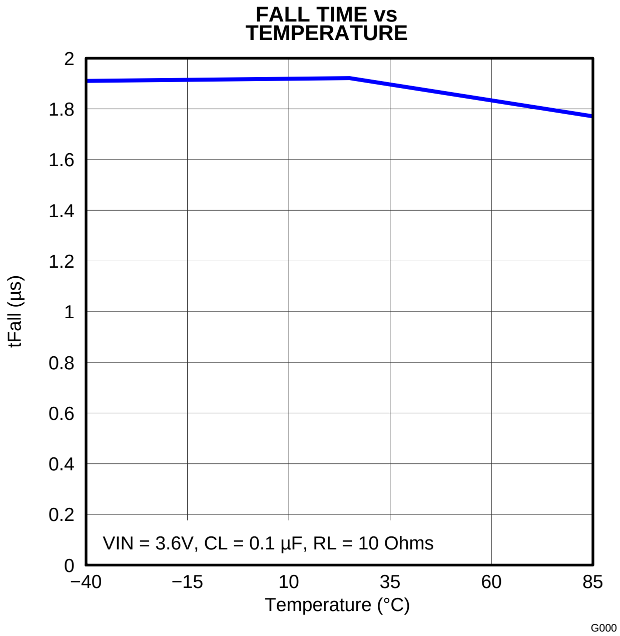


Figure 12.

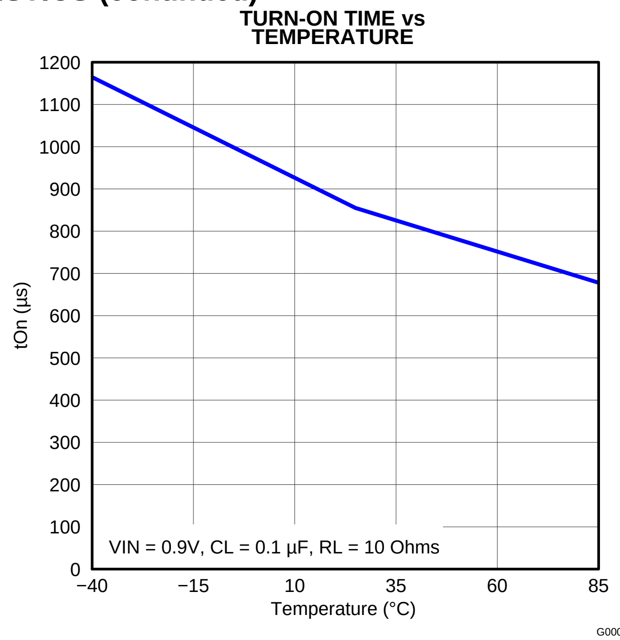


Figure 13.

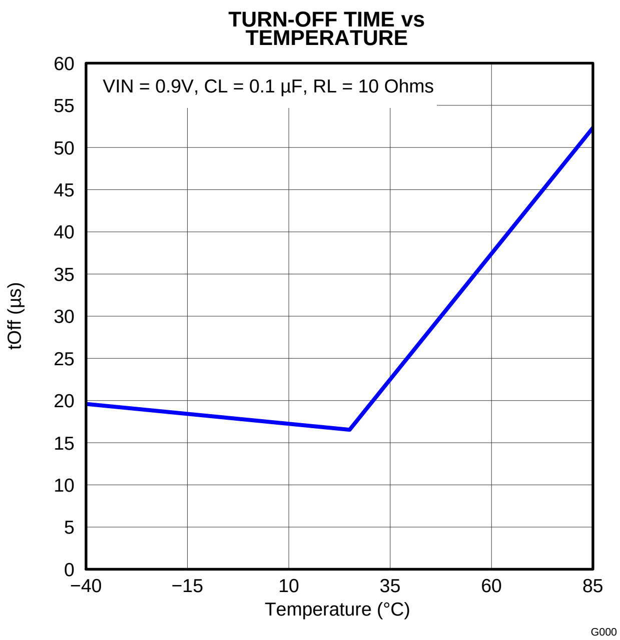


Figure 14.

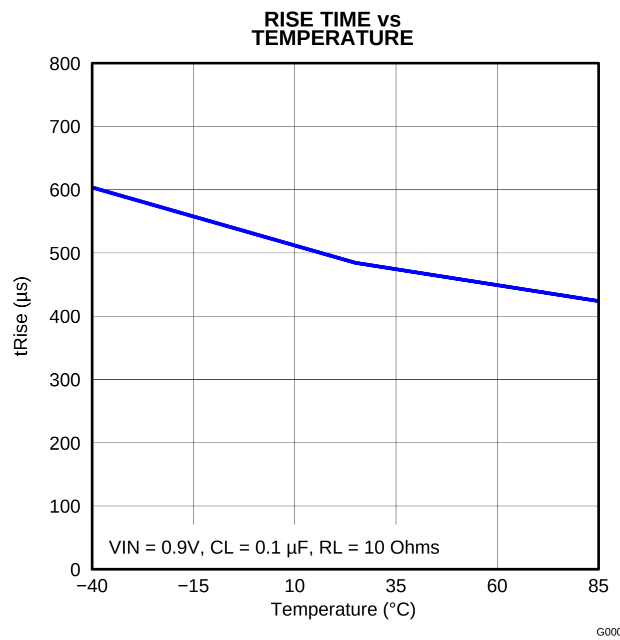


Figure 15.

TYPICAL CHARACTERISTICS (continued)

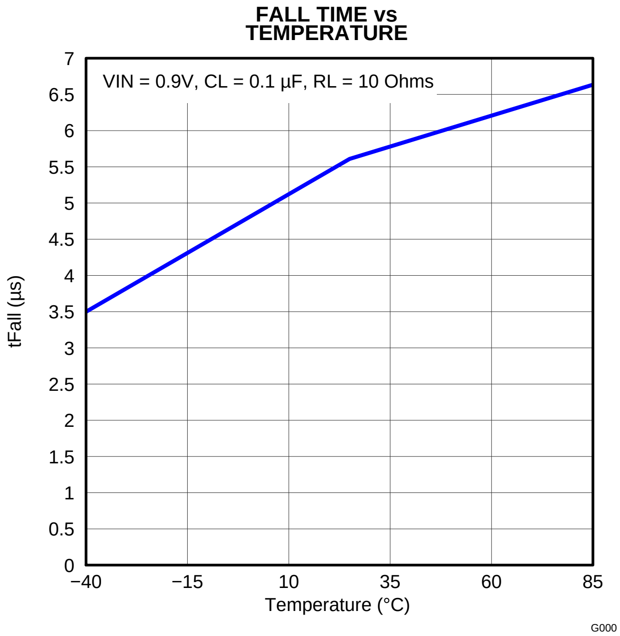


Figure 16.

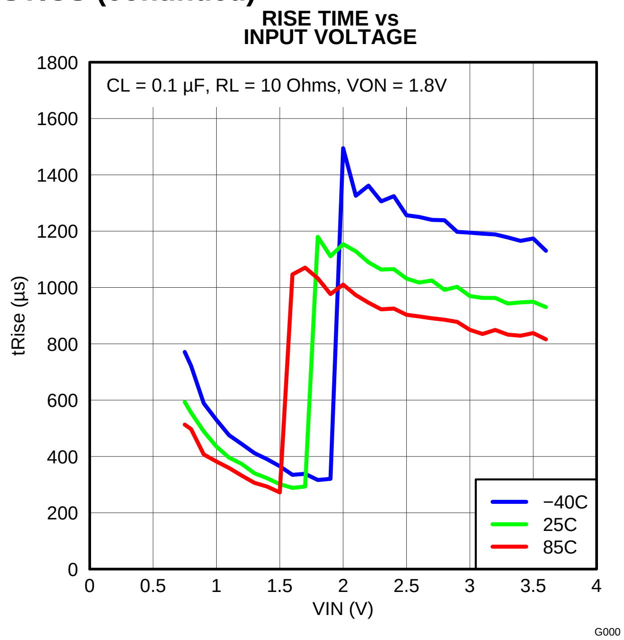


Figure 17.

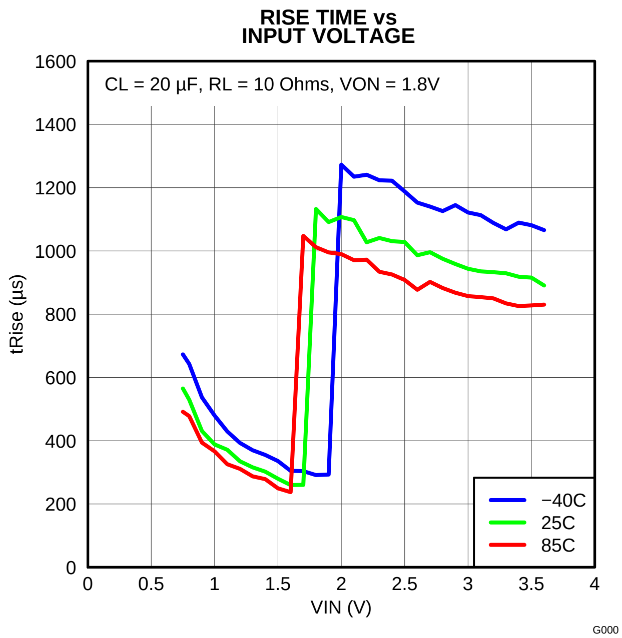


Figure 18.

TYPICAL CHARACTERISTICS (continued)

TURN-ON RESPONSE
V_{IN} = 0.9V, T_A = 25°C, C_{IN} = 1µF, C_L = 0.1µF, R_L = 10Ω

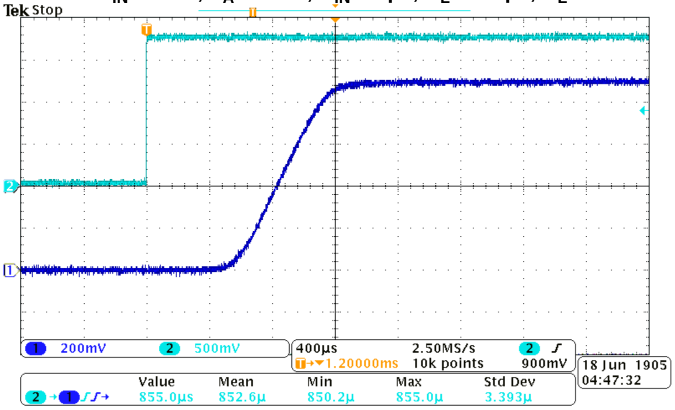


Figure 19.

TURN-OFF RESPONSE
V_{IN} = 0.9V, T_A = 25°C, C_{IN} = 1µF, C_L =0.1µF, R_L = 10Ω

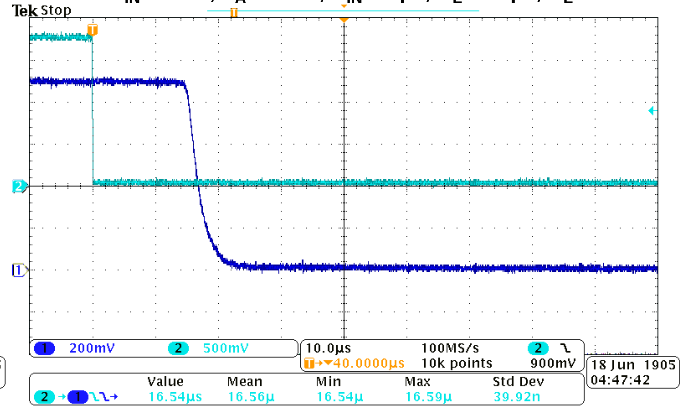


Figure 20.

TURN-ON RESPONSE
V_{IN} = 0.9V, T_A = 25°C, C_{IN} = 47µF, C_L = 20µF, R_L = 10Ω

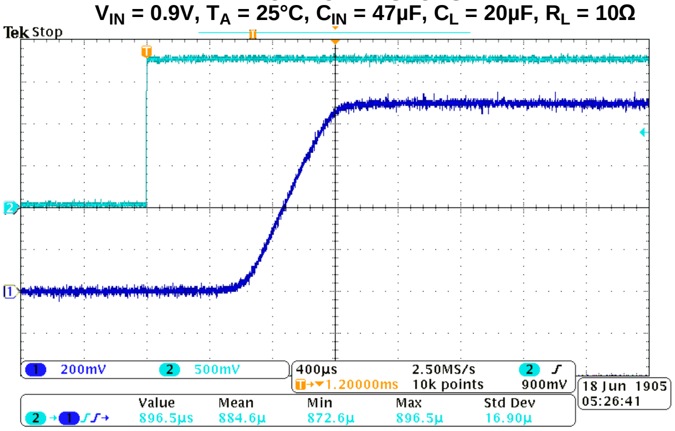


Figure 21.

TURN-OFF RESPONSE
V_{IN} = 0.9V, T_A = 25°C, C_{IN} = 47µF, C_L = 20µF, R_L = 10Ω

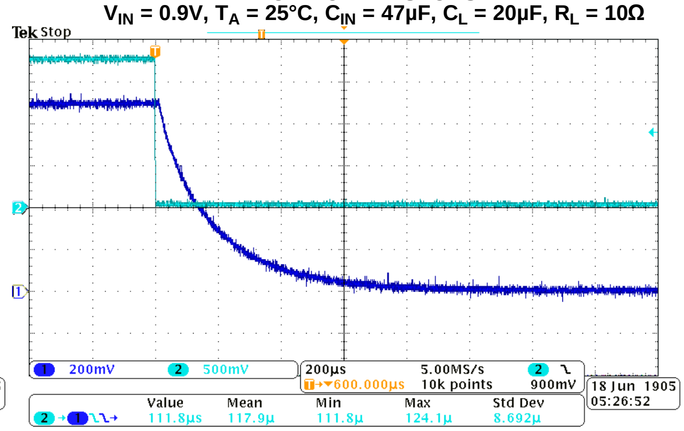


Figure 22.

TURN-ON RESPONSE
V_{IN} = 3.6V, T_A = 25°C, C_{IN} = 1µF, C_L =0.1µF, R_L = 10Ω

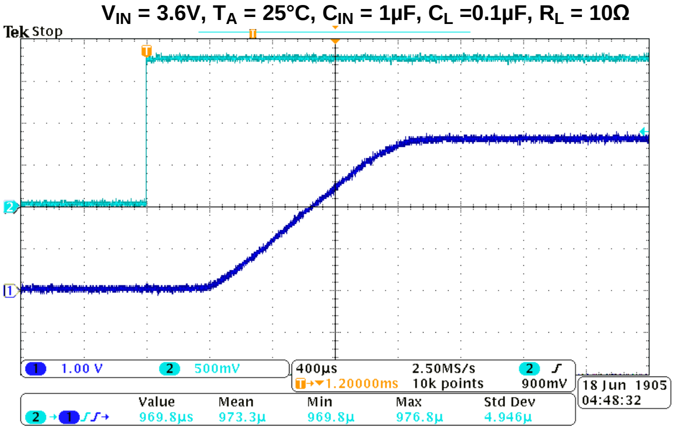


Figure 23.

TURN-OFF RESPONSE
V_{IN} = 3.6V, T_A = 25°C, C_{IN} = 1µF, C_L = 0.1µF, R_L = 10Ω

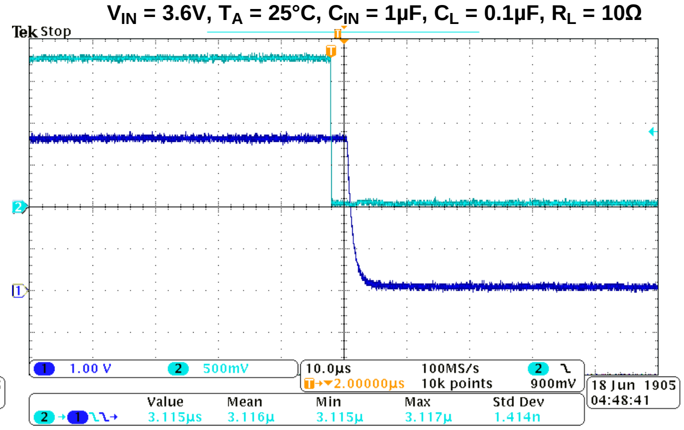


Figure 24.

TYPICAL CHARACTERISTICS (continued)

TURN-ON RESPONSE
V_{IN} = 3.6V, T_A = 25°C, C_{IN} = 47µF, C_L = 20µF, R_L = 10Ω

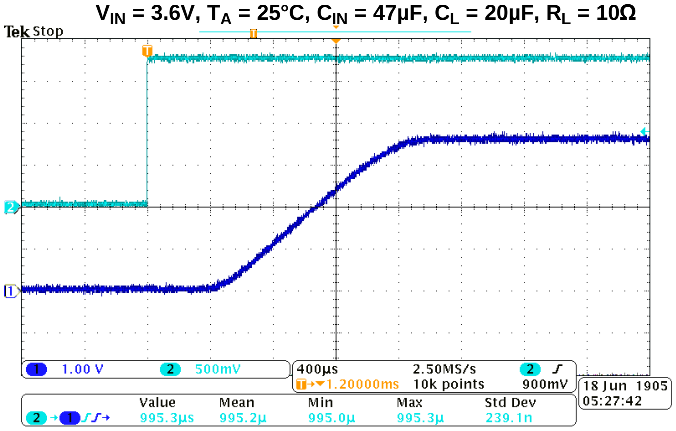


Figure 25.

TURN-OFF RESPONSE
V_{IN} = 3.6V, T_A = 25°C, C_{IN} = 47µF, C_L = 20µF, R_L = 10Ω

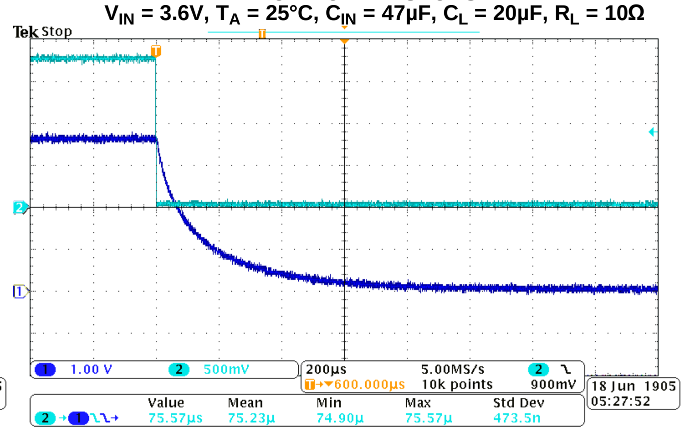


Figure 26.

APPLICATION INFORMATION

ON/OFF CONTROL

The ON pin controls the state of the switch. Asserting ON high enables the switch. ON is active high and has a low threshold, making it capable of interfacing with low-voltage signals. The ON pin is compatible with standard GPIO logic threshold. It can be used with any microcontroller with 1.2-V, 1.8-V, 2.5-V or 3.3-V GPIOs.

INPUT CAPACITOR

To limit the voltage drop on the input supply caused by transient inrush currents when the switch turns on into a discharged load capacitor or short-circuit, a capacitor needs to be placed between V_{IN} and GND. A 1-µF ceramic capacitor, C_{IN}, placed close to the pins is usually sufficient. Higher values of C_{IN} can be used to further reduce the voltage drop.

OUTPUT CAPACITOR

Due to the integral body diode in the NMOS switch, a C_{IN} greater than C_L is highly recommended. A C_L greater than C_{IN} can cause V_{OUT} to exceed VIN when the system supply is removed. This could result in current flow through the body diode from V_{OUT} to V_{IN}. A C_{IN} to C_L ratio of 10 to 1 is recommended for minimizing V_{IN} dip caused by inrush currents during startup.

OUTPUT PULL-DOWN

The output pulldown is active when the user is turning off the main pass FET. The pulldown discharges the output rail to approximately 10% of the rail, and then the output pulldown is automatically disconnected to optimize the shutdown current.

BOARD LAYOUT

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal operation. Using wide traces for V_{IN}, V_{OUT}, and GND helps minimize the parasitic electrical effects along with minimizing the case to ambient thermal impedance.

REVISION HISTORY

Changes from Original (June 2011) to Revision A	Page
• Updated swapped image issue.	8

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS22920YZPR	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	6Z	Samples
TPS22920YZPRB	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	6Z S	Samples
TPS22920YZPT	ACTIVE	DSBGA	YZP	8	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	6Z	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

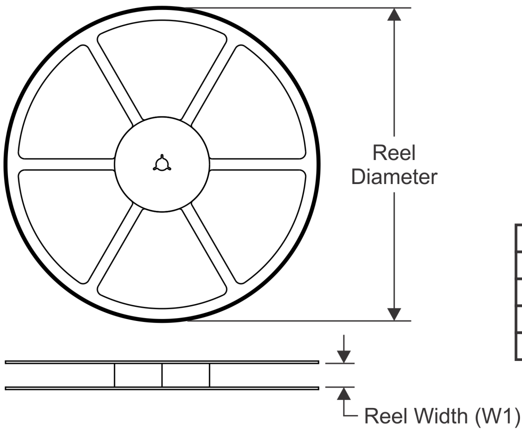
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

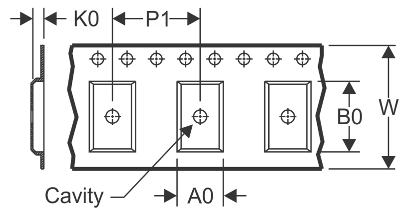
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

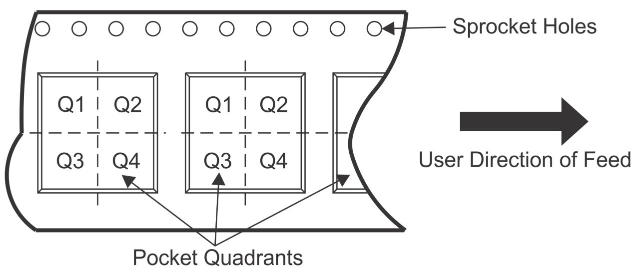


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

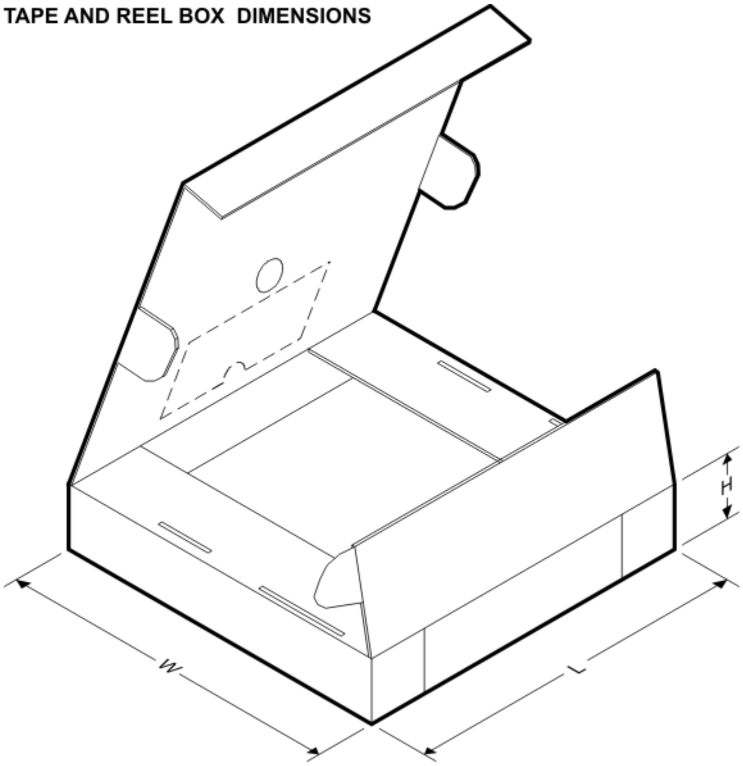
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS22920YZPR	DSBGA	YZP	8	3000	180.0	8.4	1.02	2.02	0.63	4.0	8.0	Q1
TPS22920YZPRB	DSBGA	YZP	8	3000	180.0	8.4	1.02	2.02	0.63	4.0	8.0	Q1
TPS22920YZPT	DSBGA	YZP	8	250	180.0	8.4	1.02	2.02	0.63	4.0	8.0	Q1

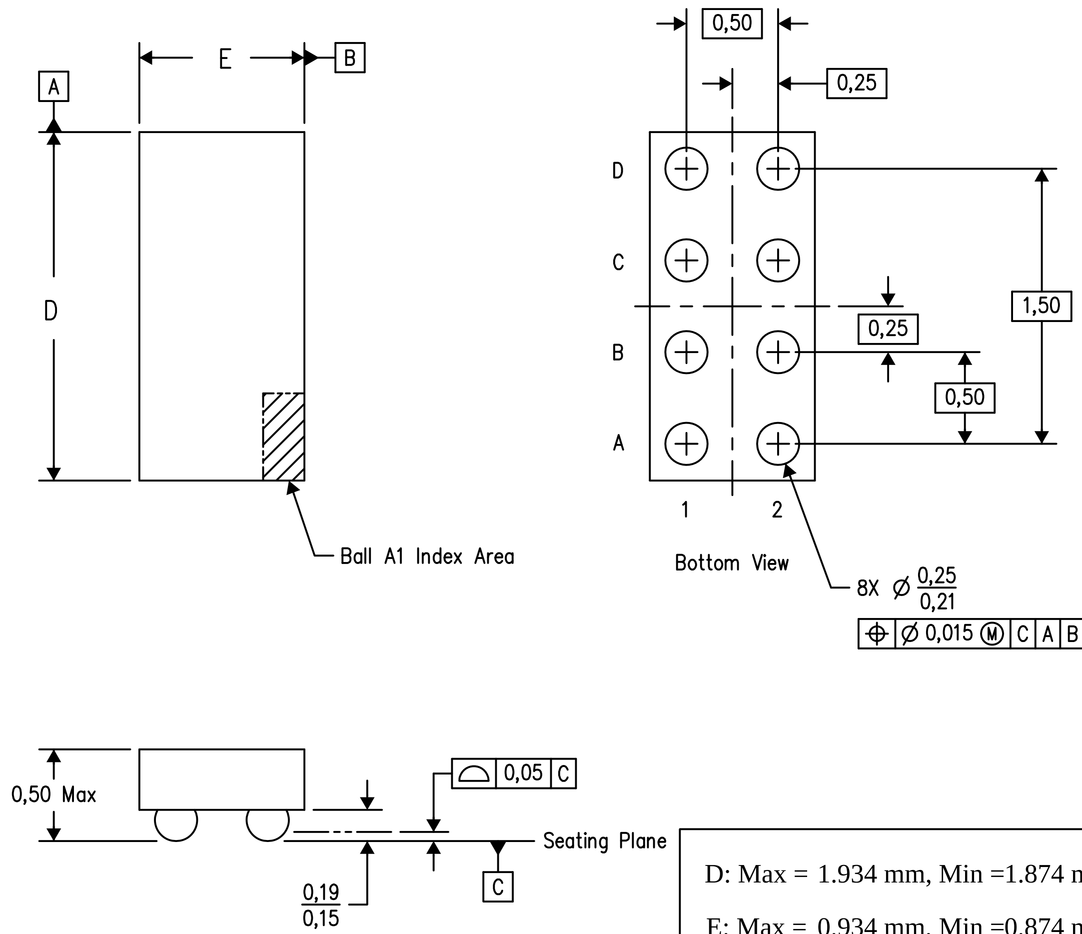
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS22920YZPR	DSBGA	YZP	8	3000	182.0	182.0	17.0
TPS22920YZPRB	DSBGA	YZP	8	3000	182.0	182.0	17.0
TPS22920YZPT	DSBGA	YZP	8	250	182.0	182.0	17.0

YZP (R–XBGA–N8) DIE–SIZE BALL GRID ARRAY



D: Max = 1.934 mm, Min =1.874 mm

E: Max = 0.934 mm, Min =0.874 mm

4204741–5/M 11/13

NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265